

150V N-Channel Enhancement Mode MOSFET

Description

The NP200S15LL uses advanced trench technology to provide excellent $R_{DS(ON)}$. This device is suitable for use as a load switch or in PWM applications.

General Features

- ◆ $V_{DS} = 150V$, $I_D = 200A$
 $R_{DS(ON)}(Typ.) = 4.9m\Omega$ @ $V_{GS} = 10V$
 $R_{DS(ON)}(Typ.) = 5.4m\Omega$ @ $V_{GS} = 4.5V$
- ◆ High power and current handling capability
- ◆ Lead free product is a acquired
- ◆ Surface mount package
- ◆ 150°C operating temperature
- ◆ 100% UIS tested

Application

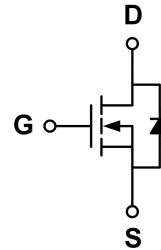
- ◆ PWM applications
- ◆ Load switch
- ◆ Uninterruptible power supply

Package

- ◆ TOLL-8L

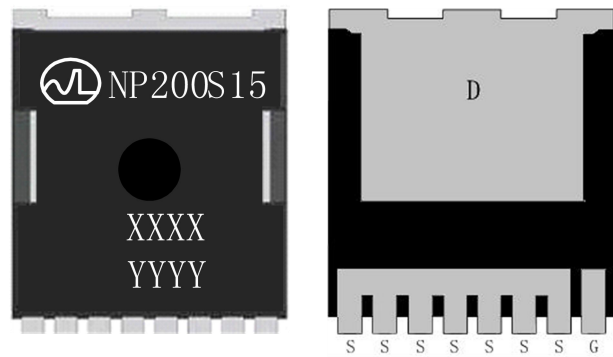


Schematic diagram



Marking and pin assignment

TOLL-8L
(Top View)



XXXX—Wafer Information
 YYYY—Quality Code

Ordering Information

Part Number	Storage Temperature	Package	Devices Per Reel
NP200S15LL-G	-55°C to +150°C	TOLL-8L	2000

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

parameter	symbol	limit	unit	
Drain-source voltage	V_{DS}	150	V	
Gate-source voltage	V_{GS}	±20	V	
Continuous Drain Current	I_D	TC=25°C	200	A
		TC=100°C	150	
Pulsed Drain Current	I_{DM}	800	A	
Avalanche energy(L=60mH)	E_{AS}	1.45	J	
Maximum power dissipation	P_D	440	W	
Operating junction Temperature range	T_j	-55—150	°C	

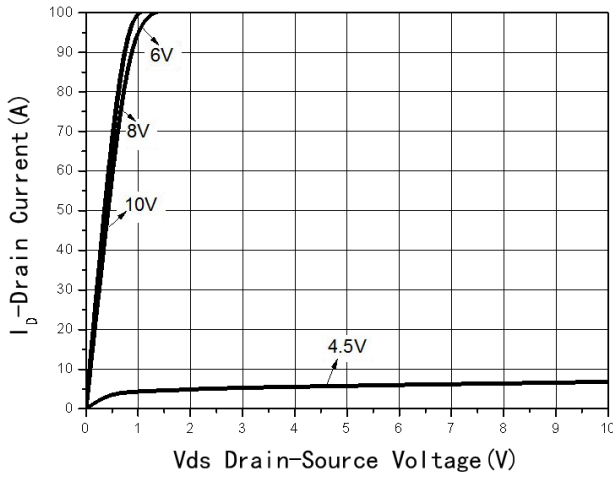
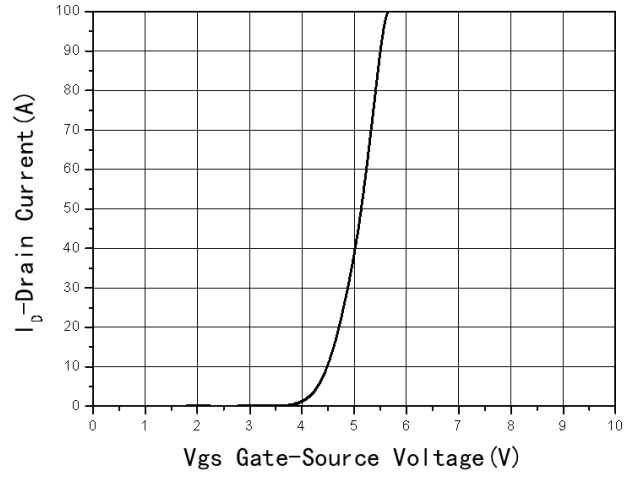
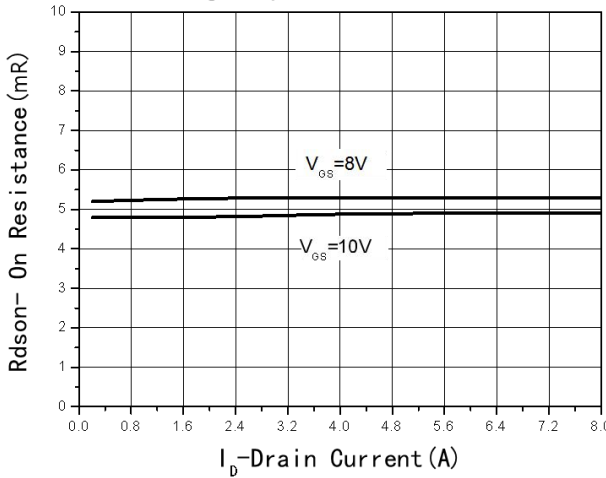
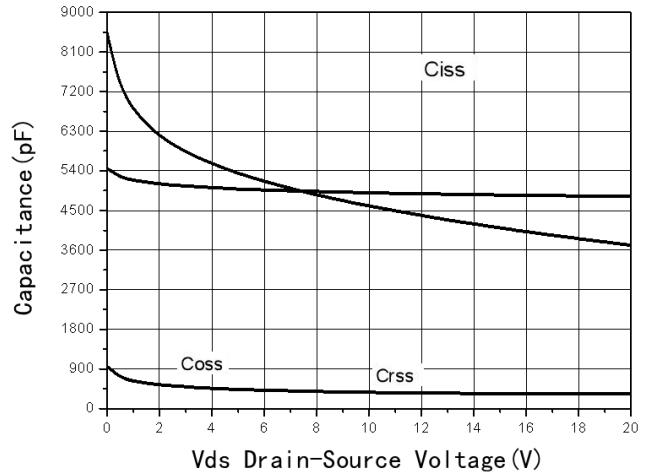
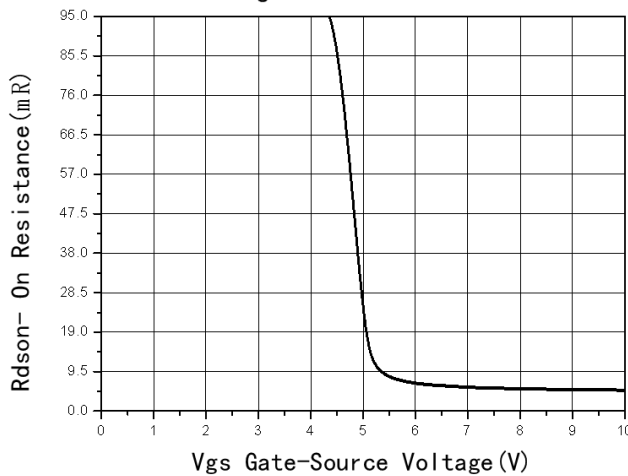
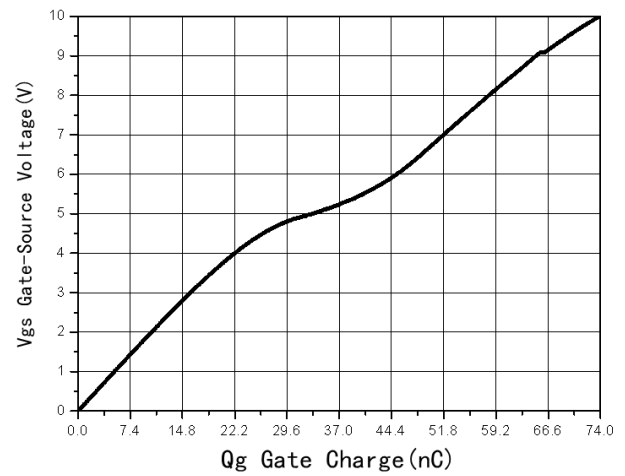
Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit	
Static Characteristics							
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	150	-	-	V	
Zero gate voltage drain current	I _{DSS}	V _{DS} =150V, V _{GS} =0V	T _J =25°C	-	-	1	μA
			T _J =85°C	-	-	30	
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA	
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2.0	3.2	4.0	V	
Drain-source on-state resistance ¹	R _{DS(ON)}	V _{GS} =10V, I _D =20A	-	4.9	7.5	mΩ	
		V _{GS} =8V, I _D =20A	-	5.4	7.7		
Diode Characteristics							
Diode Continuous Forward Current	I _S		-	-	200	A	
Reverse Recovery Time	t _{rr}	I _F =100A, V _{GS} =0V, V _{DS} =100V, di/dt=100A/us	-	268	-	ns	
Reverse Recovery Charge	Q _{rr}		-	22	-	nC	
Dynamic Characteristics²							
Intrinsic gate resistance	R _G	V _{GS} =0V, V _{DS} =0V, f=1MHz	-	3.8	-	Ω	
Input capacitance	C _{ISS}	V _{GS} =0V, V _{DS} =50V f=1.0MHz	-	4754	-	pF	
Output capacitance	C _{OSS}		-	1009	-		
Reverse transfer capacitance	C _{RSS}		-	175	-		
Turn-on delay time	t _{D(ON)}	V _{GS} =10V, V _{DS} =100V, R _G =25Ω, I _D =20A	-	20	-	ns	
Turn-on Rise time	t _r		-	34	-		
Turn-off delay time	t _{D(OFF)}		-	37	-		
Turn-off Fall time	t _f		-	25	-		
Total gate charge	Q _g	V _{GS} =10V, I _D =20A V _{DS} =100V	-	73.4	-	nC	
Gate-source charge	Q _{gs}		-	65.5	-		
Gate-drain charge	Q _{gd}		-	6.8	-		
Drain-Source Diode Characteristics							
Diode forward voltage	V _{SD}	I _{SD} =20A, V _{GS} =0V	-	0.77	1.4	V	

Note: 1: Pulse test; pulse width ≤ 300ns, duty cycle ≤ 2%.

2: Guaranteed by design, not subject to production testing.

Typical Performance Characteristics


Fig1 Output Characteristics

Fig2 Transfer Characteristics

Fig3 Rdson-Drain current

Fig4 Capacitance vs V_DS

Fig5 Rdson-Gate Drain voltage

Fig6 Gate Charge

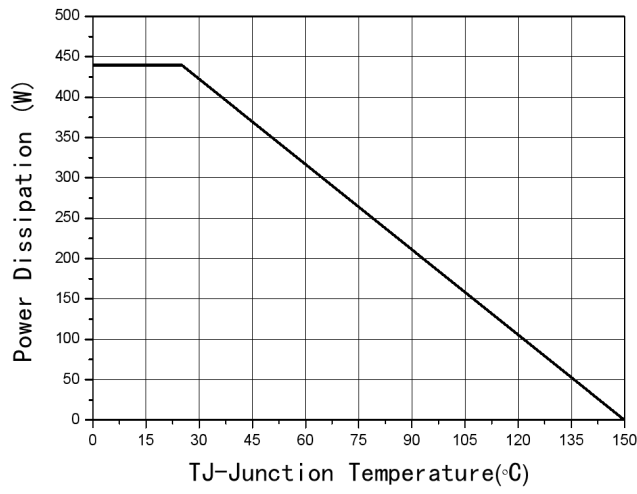


Fig7 Power De-rating

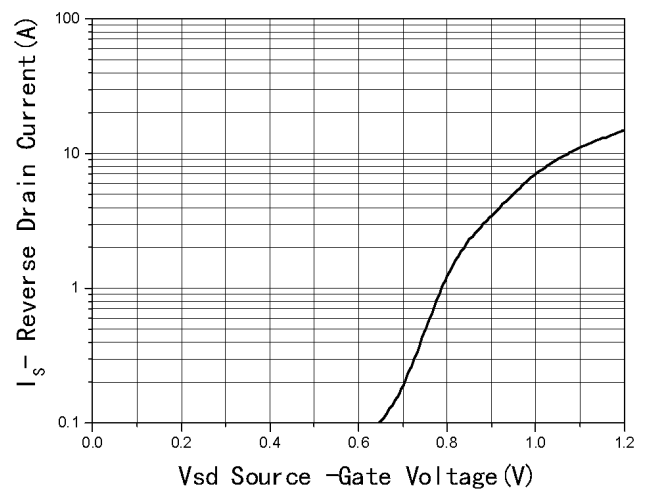
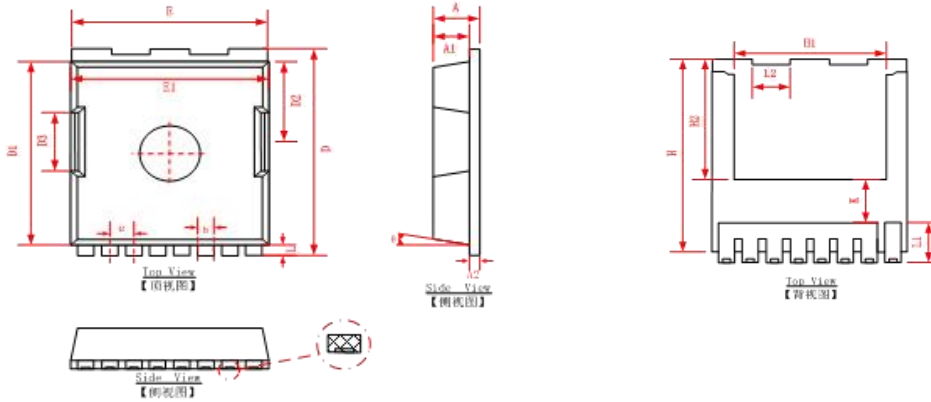


Fig8 Source-Drain Diode Forward

Package Information

● TOLL-8L



Symbol	Dimensions In Millimeters		
	Min	Ref	Max
A	2.100	2.300	2.500
A1	1.700	1.800	1.900
A2	0.400	0.500	0.600
θ	10°Ref		
D	11.500	11.600	11.700
E	9.700	9.800	9.900
D1	10.300	10.400	10.500
E1	9.800	9.900	10.000
D2	4.450	4.550	4.650
D3	3.200	3.300	3.400
e	1.200BSC		
b	0.600	0.700	0.800
L	0.500	0.600	0.700
H	10.000	11.000	12.000
H1	8.700	8.800	8.900
H2	7.250Ref		
L1	1.630	1.680	1.720
L2	2.900	3.000	3.100
K	2.650Ref		